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Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ⁶	Copy Enclosed
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Initials*	No.1	appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published		Enclosed
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	1	Probe Card Assemblies, Components Thereof and Certain Tested		
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		Same, Inv. No. 337-TA-621, Respondent Micronics Japan Co., LTD's		
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^{*} EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication

- ** Reference cited in parent application US Serial Nos. 09/527,931. (See 1.98(d).)
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- & Notice dated October 19, 2004 by Deputy Commissioner for Patent Examination Policy waiving requirement to file copies of pending US patent applications if the applications are stored in the USPTO's IFW system.
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